

MOS FIELD EFFECT TRANSISTOR

3SK255

RF AMPLIFIER FOR UHF TUNER N-CHANNEL SI DUAL GATE MOS FIELD-EFFECT TRANSISTOR 4 PINS SUPER MINI MOLD

FEATURES

• Low Vdd Use : (Vds = 3.5 V)

Driving Battery

Low Noise Figure: NF = 1.8 dB TYP. (f = 900 MHz)
High Power Gain: GPs = 18.0 dB TYP. (f = 900 MHz)

• Suitable for uses as RF amplifier in UHF TV tuner.

Automatically Mounting : Embossed Type Taping
 Small Package : 4 Pins Super Mini Mold

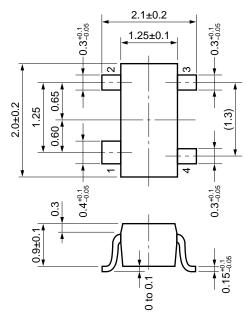
ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C)

Drain to Source Voltage	VDSX	18	V
Gate1 to Source Voltage	V _{G1} s	±8*1	V
Gate2 to Source Voltage	V _{G2} S	±8*1	V
Gate1 to Drain Voltage	V_{G1D}	18	V
Gate2 to Drain Voltage	V_{G2D}	18	V
Drain Current	lο	25	mΑ
Total Power Dissipation	Po	130	mW
Channel Temperature	Tch	125	°C
Storage Temperature	Tstg	-55 to +125	°C

*1: R_L ≥ 10 kΩ *2: Free air

PACKAGE DIMENSIONS

(Unit: mm)



PIN CONNECTIONS

- 1. Source
- 2. Drain
- 3. Gate2 4. Gate1

PRECAUTION

Avoid high static voltages or electric fields so that this device would not suffer from any damage due to those voltage or fields.



ELECTRICAL CHARACTERISTICS (TA = 25 °C)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Drain to Source Breakdown Voltage	BV _{DSX}	18			٧	$V_{G1S} = V_{G2S} = -2 \text{ V}, \text{ ID} = 10 \mu\text{A}$
Drain Current	IDSX	0.5		7.0	mA	VDS = 3.5 V, VG2S = 3 V, VG1S = 0.75 V
Gate1 to Source Cutoff Voltage	VG1S(off)	-1.0	0	+1.0	٧	$V_{DS} = 3.5 \text{ V}, V_{G2S} = 3 \text{ V}, I_{D} = 10 \mu A$
Gate2 to Source Cutoff Voltage	V _{G2S(off)}	0	0.5	1.0	٧	$V_{DS} = 3.5 \text{ V}, V_{G1S} = 3 \text{ V}, I_{D} = 10 \mu A$
Gate1 Reverse Current	I _{G1SS}			±20	nA	VDS = 0, VG2S = 0, VG1S = ±6 V
Gate2 Reverse Current	I _{G2} ss			±20	nA	VDS = 0, VG1S = 0, VG2S = ±6 V
Forward Transfer Admittance	yfs	14	19	24	mS	$V_{DS} = 3.5 \text{ V}, V_{G2S} = 3 \text{ V}, I_{D} = 7 \text{ mA}$ $f = 1 \text{ kHz}$
Input Capacitance	Ciss	1.2	1.7	2.2	pF	V 05VV 0VI 7
Output Capacitance	Coss	0.5	1.0	1.5	pF	$V_{DS} = 3.5 \text{ V}, V_{G2S} = 3 \text{ V}, I_{D} = 7 \text{ mA}$ $f = 1 \text{ MHz}$
Reverse Transfer Capacitance	Crss		0.01	0.03	pF	1 - 1 Will2
Power Gain	Gps	15	18	21	dB	VDS = 3.5 V, VG2S = 3 V, ID = 7 mA
Noise Figure	NF		1.8	3.0	dB	f = 900 MHz

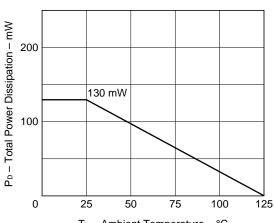
IDSX Classification

Rank	U1G			
Marking	U1G			
IDSX (mA)	0.5 to 7.0			

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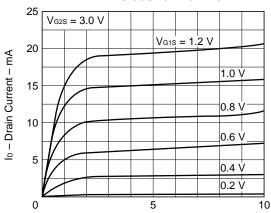
TYPICAL CHARACTERISTICS (TA = 25 °C)





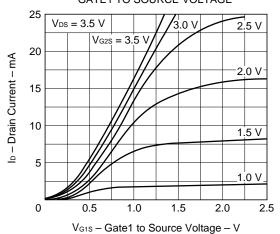
$T_{\text{A}}-Ambient\ Temperature-^{\circ}C$

DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE

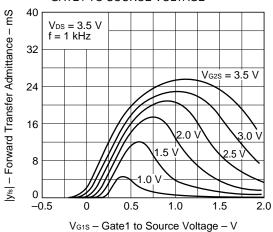


V_{DS} - Drain to Source Voltage - V

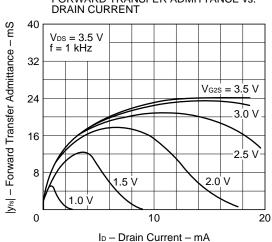
DRAIN CURRENT vs. GATE1 TO SOURCE VOLTAGE



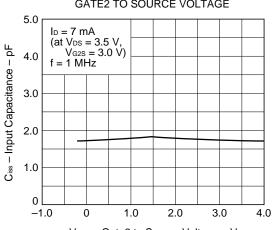
FORWARD TRANSFER ADMITTANCE vs. GATE1 TO SOURCE VOLTAGE



FORWARD TRANSFER ADMITTANCE vs.

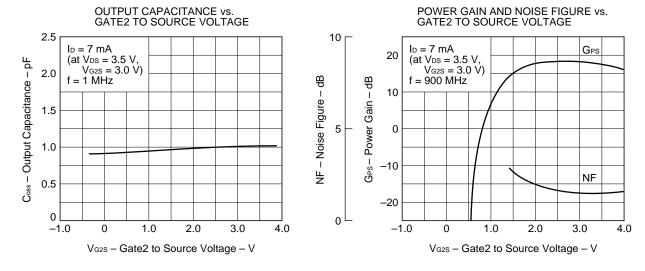


INPUT CAPACITANCE vs. GATE2 TO SOURCE VOLTAGE



V_{G2S} - Gate2 to Source Voltage - V



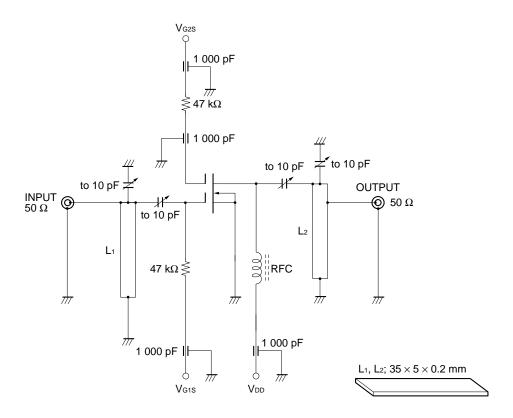


S-Parameter

 $V_{DS} = 3.5 V$, $V_{G2S} = 3 V$, $I_{D} = 7 mA$

Frequency	S11		S21		S12		S22	
(MHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
100	1.017	-6.5	2.057	173.3	0.035	-88.2	0.985	-2.9
200	1.000	-13.4	2.034	163.6	0.014	-121.6	0.987	-6.9
300	0.999	-19.8	1.991	155.5	0.006	67.0	0.988	-10.4
400	0.993	-26.6	1.996	146.8	0.006	71.3	0.983	-13.8
500	0.984	-32.6	1.956	136.7	0.005	117.8	0.985	-17.1
600	0.966	-39.1	1.930	130.4	0.002	-23.3	0.983	-20.8
700	0.948	-45.5	1.901	122.7	0.002	-162.4	0.979	-24.6
800	0.934	-51.4	1.897	114.5	0.003	37.8	0.986	-27.9
900	0.908	-57.5	1.897	105.6	0.011	-146.3	0.991	-32.1
1000	0.901	-83.8	1.984	96.6	0.010	-144.3	1.024	-36.4

GPS AND NF TEST CIRCUIT AT f = 900 MHz



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Anti-radioactive design is not implemented in this product.

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